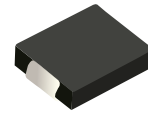
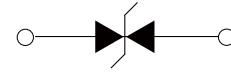


FEATURES

- | Low profile package
- | Ideal for automated placement
- | 3000 Watt peak pulse power capability with a 10/1000µs waveform
- | For surface mounted applications to optimize board space
- | Excellent clamping capability
- | Very fast response time
- | Low incremental surge resistance



DO-214AB(SMC)



Schematic Symbol

APPLICATIONS

- | Power supply protection
- | Automotive application
- | Industrial application
- | Power management

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS (T_A=25°C)

Parameter	Symbo	Value	Unit
Peak Pulse Power Dissipation on 10/1000µs waveform (Note1, Note2).	P _{PPM}	3000	Watts
Steady State Power Dissipation at T _L =50°C, Lead lengths.375" (9.5mm) (Note2)	P _D	6.5	Watts

- Notes :** 1.Non-repetitive current pulse,T_A=25°C.
 2.Mounted on 5.0mm*5.0mm (0.03mm thick) Copper Pads to each terminal.

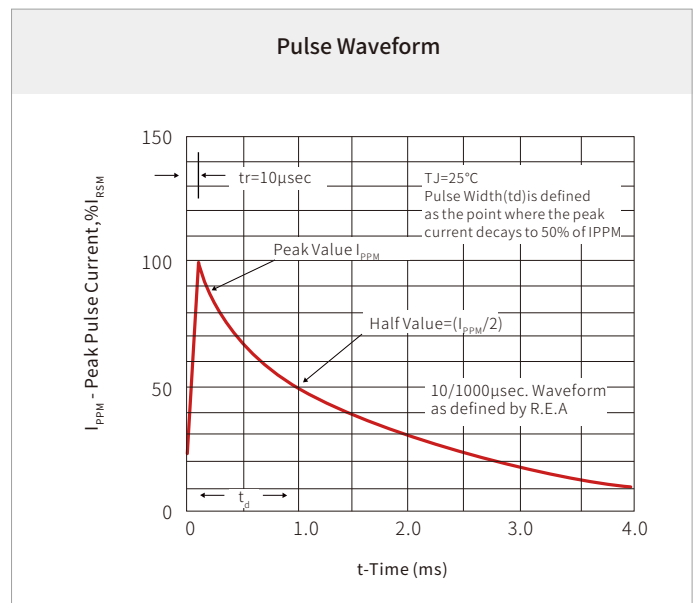
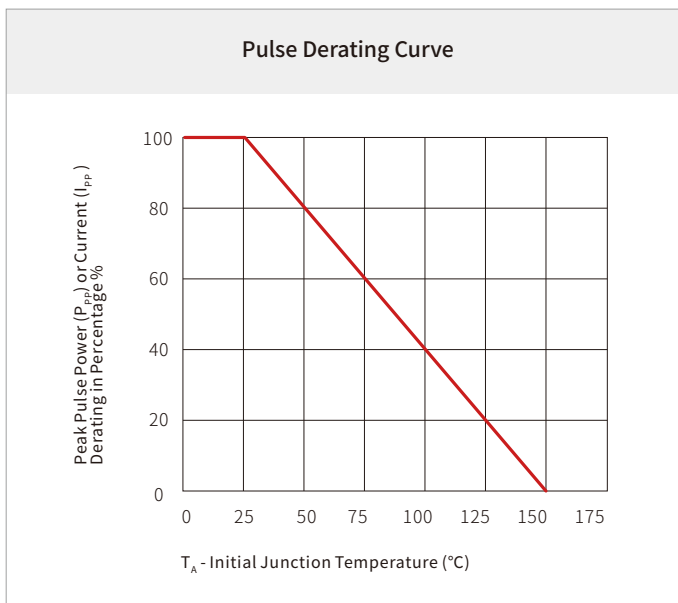
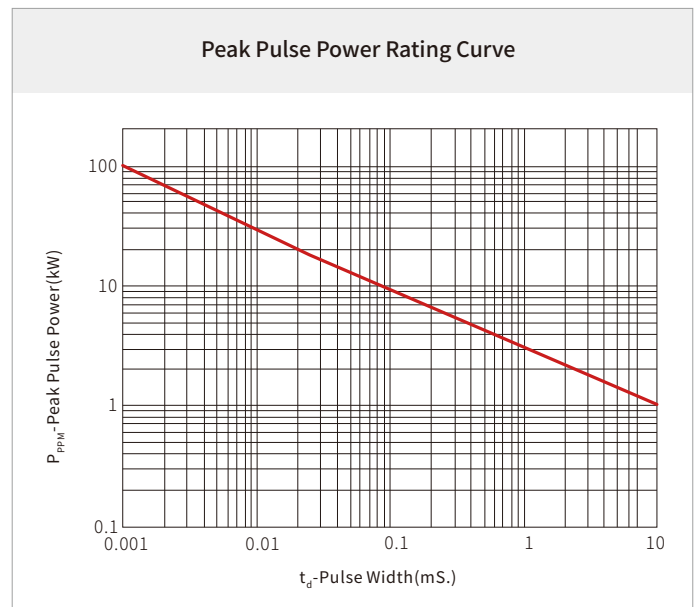
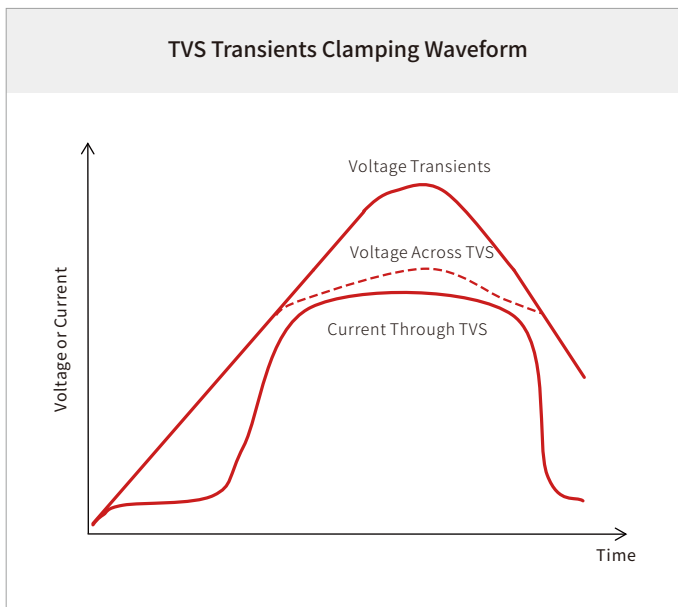
THERMAL CONSIDERATIONS

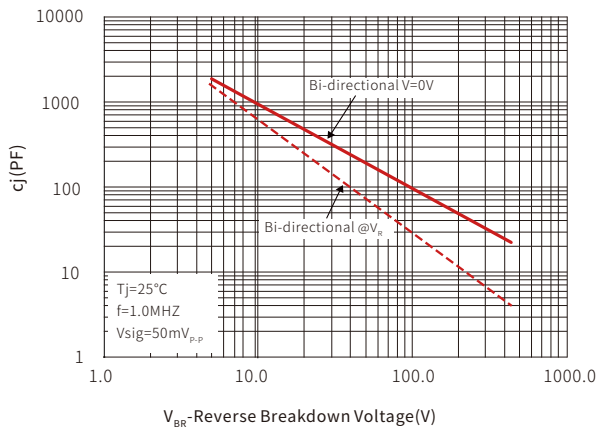
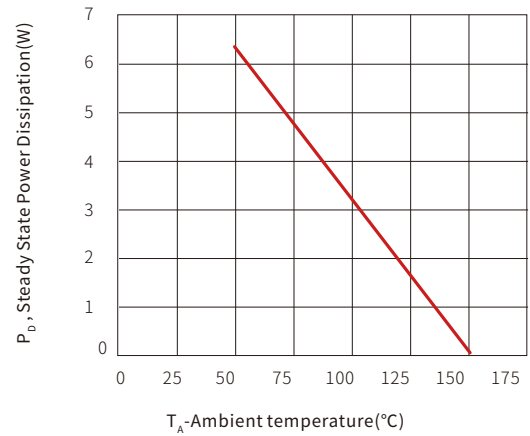
Parameter	Symbol	Value	Unit
Operating Junction Temperature	T _J	-55 to +150	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C
Junction to Ambient on printed circuit	R _{θJA}	75	°C/W

ELECTRICAL CHARACTERISTICS (T_A=25°C)

Part Number	Device Marking Code	Reverse Stand-off Voltage	Breakdown Voltage Min.@I _T	Breakdown Voltage Max.@I _T	Test Current	Maximum Clamping Voltage @I _{PP}	Peak Pulse Current	Reverse Leakage @V _{RWM}
		V _{RWM} (V)	V _{BR} (V)	V _{BR} (V)	I _T (mA)	V _C (V)	I _{PP} (A)	I _R (μA)
SVC300B70	DGP	70.0	77.8	86.0	1.0	113.0	26.5	2.0

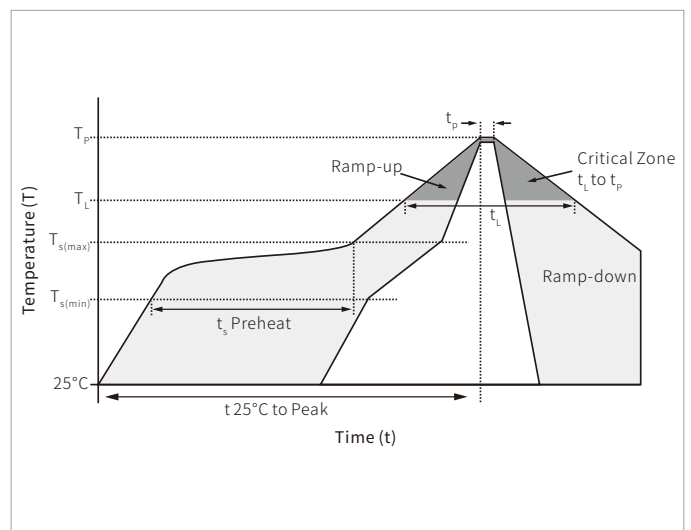
CHARACTERISTIC CURVES



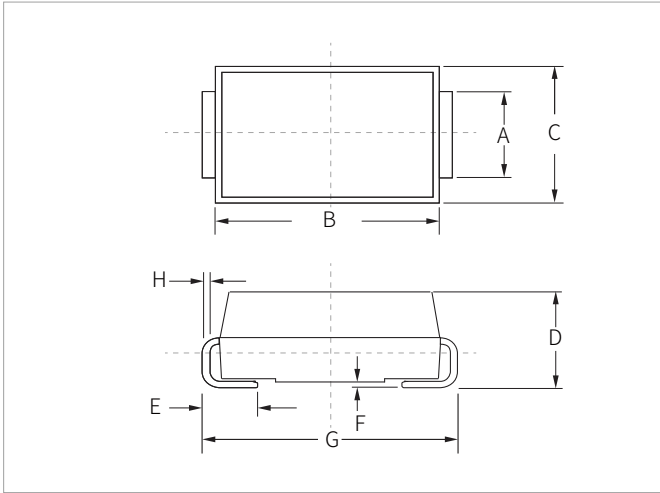
Typical Junction Capacitance

Steady State Power Dissipation Derating Curve


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_r)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

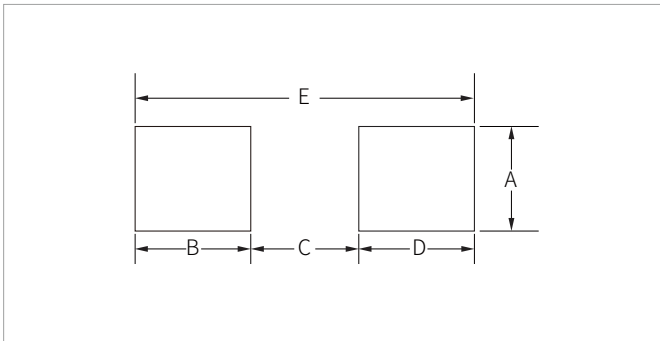


DO-214AB(SMC) PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.80	3.20	0.110	0.126
B	6.60	7.20	0.260	0.283
C	5.70	6.10	0.224	0.240
D	2.15	2.75	0.085	0.108
E	1.00	1.60	0.039	0.063
F	0.02	0.20	0.000	0.008
G	7.60	8.00	0.299	0.315
H	0.15	0.30	0.006	0.012

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	-	0.129	-
B	2.40	-	0.094	-
C	-	4.20	-	0.165
D	2.40	-	0.094	-
E	8.20REF		0.323REF	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SVC300B70	DO-214AB(SMC)	3000PCS	13"

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